

Rev. V1

#### **Features**

- Designed for MRI applications
- Non-Magnetic Surface Mount Package
- Anti-Parallel Self Bias Configuration
- $C_T = 3.0 \text{ pF}, R_P = 10 \text{ k}\Omega, V_B = 80 \text{ V}$
- > 50 W CW Incident Power Handling @ 400 MHz
- Lead-Free 4 mm 8-lead HQFN Package
- Halogen-Free "Green" Mold Compound
- RoHS\* Compliant and 260°C Reflow Compatible

#### **Description**

The MADP-011048 acts as a passive switch using silicon PIN diodes in a non-magnetic surface mount package. There are two sets of diode pairs constructed in an anti-parallel configuration that operate from 5 to 400 MHz.

The two pairs of diodes are arranged in an electrically isolated anti-parallel configuration. The diode pair with anode on Pin 1 and cathode on Pin 6 will be referenced as D1 and the diode pair with anode on Pin 5 and cathode on Pin 2 will be referenced as D2.

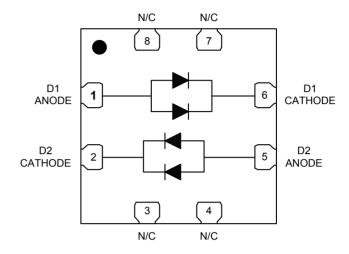
The MADP-011048 is well suited for MRI passive switching applications. The PIN diodes become a high Q R-C network under small signal and behave as an effective passive rectifier or short circuit under high RF signal to tune and de-tune the resonant MRI tank circuit. The anti-parallel doublet configuration provides efficient power handling.

## Ordering Information<sup>1,2</sup>

Part Number	Package
MADP-011048-TR3000	3000 Piece Reel
MADP-011048-000SMB	Sample Board

- 1. Reference Application Note M513 for reel size information.
- 2. All sample boards include 5 loose parts.

#### **Functional Schematic**



### Pin Configuration<sup>3</sup>

Pin No.	Function		
1	D1 Anode		
2	D2 Cathode		
3	No Connection		
4	No Connection		
5	D2 Anode		
6	D1 Cathode		
7	No Connection		
8	No Connection		
Paddle <sup>4</sup>	Ground		

- MACOM recommends connecting unused package pins to ground.
- The exposed pad centered on the package bottom must be connected to RF, DC and thermal ground.

<sup>\*</sup> Restrictions on Hazardous Substances, European Union Directive 2011/65/EU.



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## Electrical Specifications<sup>5</sup>: $T_A = 25^{\circ}C$ , $Z_0 = 50 \Omega$

Parameter	Test Conditions	Units	Min.	Тур.	Max.
Total Capacitance (C <sub>T</sub> )	100 MHz, 0 V	pF	_	3.0	4.0
Series Resistance (R <sub>S</sub> )	100 MHz, +10 mA	Ω	_	0.5	_
Parallel Resistance (R <sub>P</sub> )	100 MHz, 0 V	kΩ	_	10	_
Reverse Breakdown Voltage	-10 μΑ	V	_	100	_
Forward Voltage	+10 mA	V	_	0.85	_
Carrier Lifetime	1 kHz, +10 mA, -6 mA	μs	_	0.2	_
CW Thermal Resistance (O <sub>JC</sub> )	(Infinite heat sink at thermal ground plane)	°C/W	_	22	_
Insertion Loss	100 MHz, +10 mA	dB	_	0.05	_
Input/output Return Loss	100 MHz, +10 mA	dB	_	30	_
Isolation	100 MHz, 0 V	dB	_	14	_

<sup>5.</sup> Per diode pair D1 or D2

### **Absolute Maximum Ratings**<sup>6,7</sup>

Parameter	Absolute Maximum		
CW Incident Power +50 mA, 400 MHz @ 85°C	+51 dBm		
Reverse Voltage	80 V		
AC <sub>RMS</sub> + DC Forward Current (per diode pair D1 or D2)	3.7 A		
Power Dissipation (per diode pair D1 or D2)	4.7 W		
Junction Temperature <sup>8</sup>	+175°C		
Operating Temperature	-55°C to +125°C		
Storage Temperature	-55°C to +125°C		

Exceeding any one or combination of these limits may cause permanent damage to this device.

### **Handling Procedures**

Please observe the following precautions to avoid damage:

#### **Static Sensitivity**

These devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these class 2 devices.

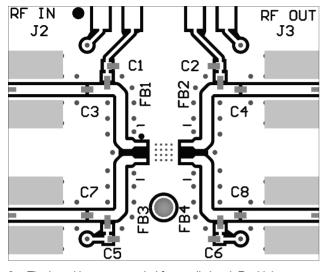
MACOM does not recommend sustained operation near these survivability limits.

Operating at nominal conditions with T<sub>J</sub> ≤ +175°C will ensure MTTF > 1 x 10<sup>6</sup> hours.



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### Low Power Sample Board (< +20 dBm³)



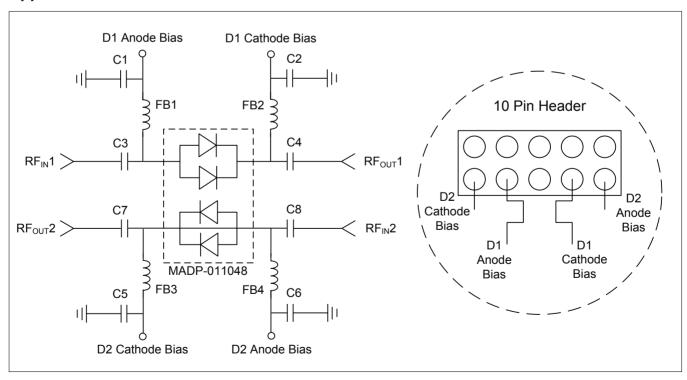
The board is recommended for small signal. For high power operation, heat sink is required.

#### Parts List: 100 - 400 MHz

Part	Value	Case Style
C1,C2,C5,C6	100 pF	0402
C3, C4, C7, C8	1 μF <sup>10</sup>	0402
Ferrite Bead: FB1,FB2,FB3,FB4	1000 Ω AC Resistance @ 1 GHz <sup>11</sup>	0402

- 10. These values are recommended for 100 400 MHz operation. Increase capacitance to 10  $\mu F$  for operation below 100 MHz.
- 11. Recommended part: Murata BLM15HD102SN1

### **Application Schematic**



# **MADP-011048**

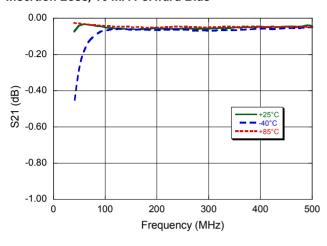


# Dual Pair Anti-Parallel Non-Magnetic PIN 5 - 400 MHz

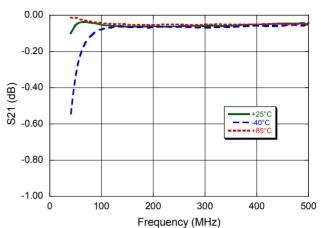
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## Typical Performance Curves<sup>12</sup>

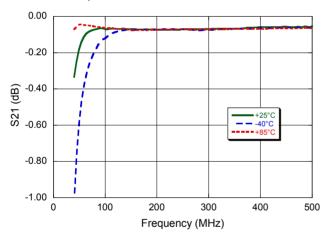
#### Insertion Loss, 10 mA Forward Bias



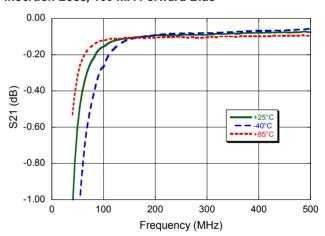
#### Insertion Loss, 20 mA Forward Bias



#### Insertion Loss, 50 mA Forward Bias



#### Insertion Loss, 100 mA Forward Bias



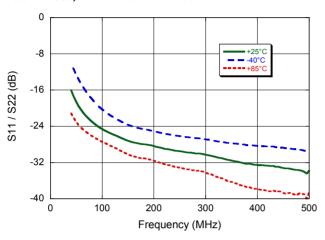
12. Performance below 100 MHz is limited by sample board bias components.



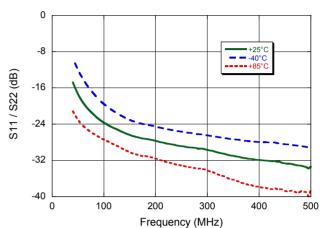
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## **Typical Performance Curves** 13

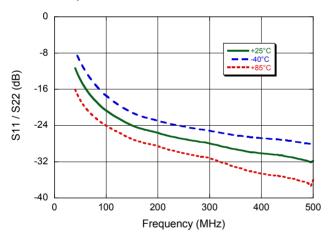
#### Return Loss, 10 mA Forward Bias



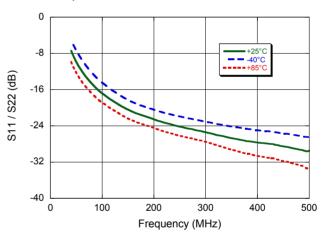
#### Return Loss, 20 mA Forward Bias



#### Return Loss, 50 mA Forward Bias



#### Return Loss, 100 mA Forward Bias



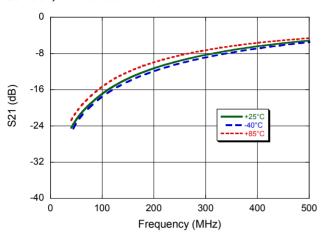
13. Performance below 100 MHz is limited by sample board bias components.



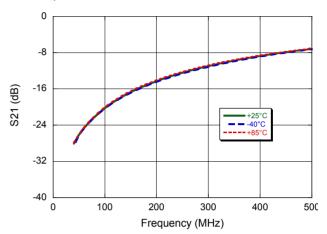
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## **Typical Performance Curves**<sup>14</sup>

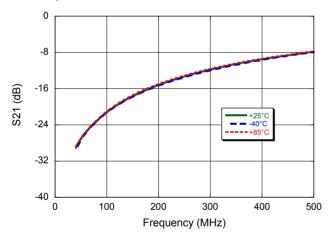
#### Isolation, 0 V Reverse Bias



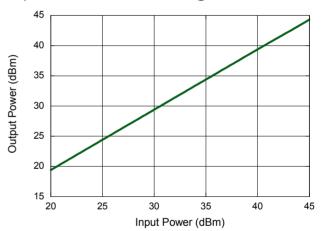
#### Isolation, 10 V Reverse Bias



#### Isolation, 40 V Reverse Bias



#### Output Power vs. Incident Power @ 400 MHz CW

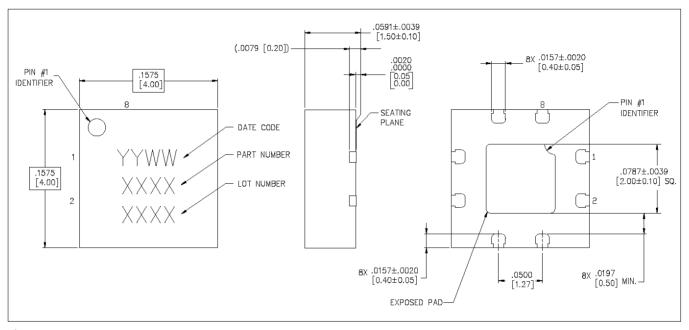


14. Performance below 100 MHz is limited by sample board bias components.



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### Lead-Free 4 mm 8-Lead HQFN<sup>†</sup>



<sup>†</sup> Reference Application Note S2083 for lead-free solder reflow recommendations. Meets JEDEC moisture sensitivity level 1 requirements. Plating is 100% matte tin over copper.

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MADP-011048-TR3000